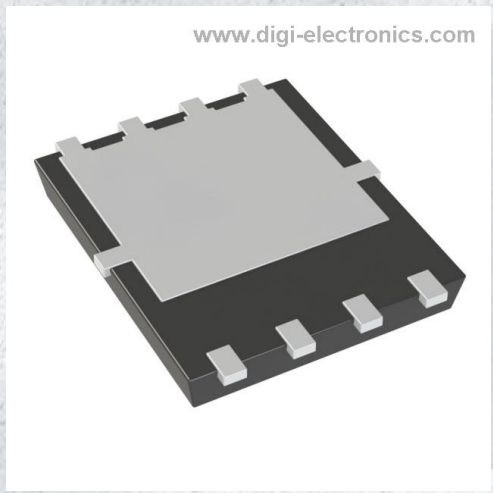
AON6370 Datasheet



https://www.DiGi-Electronics.com

DiGi Electronics Part Number	AON6370-DG
Manufacturer	Alpha & Omega Semiconductor Inc.
Manufacturer Product Number	AON6370
Description	MOSFET N-CH 30V 23A/47A 8DFN
Detailed Description	N-Channel 30 V 23A (Ta), 47A (Tc) 6.2W (Ta), 26W (Tc) Surface Mount 8-DFN (5x6)

Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

Purchase and inquiry

Manufacturer Product Number:	Manufacturer:
AON6370	Alpha & Omega Semiconductor Inc.
Series:	Product Status:
-	Obsolete
FET Type:	Technology:
N-Channel	MOSFET (Metal Oxide)
Drain to Source Voltage (Vdss):	Current - Continuous Drain (Id) @ 25°C:
30 V	23A (Ta), 47A (Tc)
Drive Voltage (Max Rds On, Min Rds On):	Rds On (Max) @ Id, Vgs:
4.5V, 10V	7.2mOhm @ 20A, 10V
Vgs(th) (Max) @ Id:	Gate Charge (Qg) (Max) @ Vgs:
2.2V @ 250µA	13 nC @ 10 V
Vgs (Max):	Input Capacitance (Ciss) (Max) @ Vds:
±20V	840 pF @ 15 V
FET Feature:	Power Dissipation (Max):
-	6.2W (Ta), 26W (Tc)
Operating Temperature:	Mounting Type:
-55°C ~ 150°C (TJ)	Surface Mount
Supplier Device Package:	Package / Case:
8-DFN (5x6)	8-PowerSMD, Flat Leads
Base Product Number:	
AON63	

Environmental & Export classification

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	
8541.29.0095	

ALPHA & OMEGA SEMICONDUCTOR

AON6370

30V N-Channel MOSFET

General Description

- Trench Power αMOS Technology
- Low $R_{DS(ON)}$
- Low Gate Charge
- High Current Capability
- RoHS and Halogen-Free Compliant

Applications

- DC/DC Converters in Computing
- Isolated DC/DC Converters in Telecom and Industrial
- See Note I

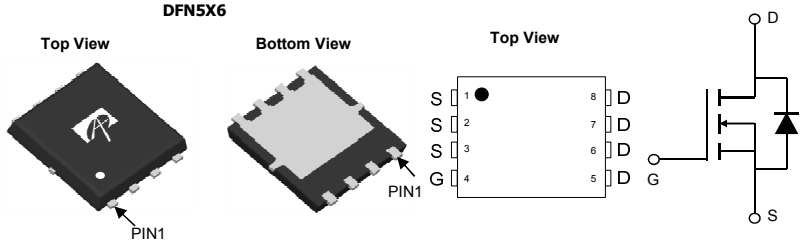
Product Summary

V_{DS}	30V
I_D (at V_{GS}=10V)	47A
$R_{DS(ON)}$ (at V_{GS}=10V)	< 7.2mΩ
$R_{DS(ON)}$ (at V_{GS}=4.5V)	< 11.5mΩ

100% UIS Tested
100% Rg Tested

Green Product

DFN5X6



Orderable Part Number	Package Type	Form	Minimum Order Quantity
AON6370	DFN 5x6	Tape & Reel	3000

Absolute Maximum Ratings T_A=25°C unless otherwise noted

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current	T_C=25°C	I_D	47	A
	T_C=100°C		29	
Pulsed Drain Current [C]		I_{DM}	90	
Continuous Drain Current	T_A=25°C	I_{DSM}	23	A
	T_A=70°C		18	
Avalanche Current [C]		I_{AS}	40	A
Avalanche energy	L=0.01mH [C]	E_{AS}	8	mJ
V_{DS} Spike	10µs	V_{SPIKE}	36	V
Power Dissipation [B]	T_C=25°C	P_D	26	W
	T_C=100°C		10	
Power Dissipation [A]	T_A=25°C	P_{DSM}	6.2	W
	T_A=70°C		4	
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter		Symbol	Typ	Max	Units
Maximum Junction-to-Ambient [A]	t ≤ 10s	$R_{\theta JA}$	15	20	°C/W
Maximum Junction-to-Ambient [A D]	Steady-State		40	50	°C/W
Maximum Junction-to-Case	Steady-State	$R_{\theta JC}$	3.8	4.8	°C/W

ALPHA & OMEGA SEMICONDUCTOR

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	ID=250µA, VGS=0V	30			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=30V, V_{GS}=0V			1	µA
		T_J=55°C			5	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}=±20V			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=250µA	1.4	1.8	2.2	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V, I_D=20A		5.8	7.2	mΩ
		T_J=125°C		8.7	10.5	
		V_{GS}=4.5V, I_D=20A		9	11.5	mΩ
g_{FS}	Forward Transconductance	V_{DS}=5V, I_D=20A		62		S
V_{SD}	Diode Forward Voltage	I_S=1A,V_{GS}=0V		0.71	1	V
I_S	Maximum Body-Diode Continuous Current				30	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=15V, f=1MHz		840		pF
C_{oss}	Output Capacitance			330		pF
C_{rss}	Reverse Transfer Capacitance			50		pF
R_g	Gate resistance	f=1MHz	0.6	1.2	1.8	Ω
SWITCHING PARAMETERS						
Q_g(10V)	Total Gate Charge	V_{GS}=10V, V_{DS}=15V, I_D=20A		13		nC
Q_g(4.5V)	Total Gate Charge			6.2		nC
Q_{gs}	Gate Source Charge			2.5		nC
Q_{gd}	Gate Drain Charge			3.5		nC
Q_{gs}	Gate Source Charge	V_{GS}=4.5V, V_{DS}=15V, I_D=20A		2.5		nC
Q_{gd}	Gate Drain Charge			3.5		nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=10V, V_{DS}=15V, R_L=0.75Ω, R_{GEN}=3Ω		5.5		ns
t_r	Turn-On Rise Time			3		ns
$t_{D(off)}$	Turn-Off DelayTime			17		ns
t_f	Turn-Off Fall Time			3		ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=20A, dI/dt=500A/µs		11		ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=20A, dI/dt=500A/µs		18		nC

A. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A =25° C. The Power dissipation P_{DSM} is based on $R_{\theta JA}$ t≤ 10s and the maximum allowed junction temperature of 150° C. The value in any given application depends on the user's specific board design.
B. The power dissipation P_D is based on $T_{J(MAX)}$=150° C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
C. Single pulse width limited by junction temperature $T_{J(MAX)}$=150° C.
D. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to case $R_{\theta JC}$ and case to ambient.
E. The static characteristics in Figures 1 to 6 are obtained using <300µs pulses, duty cycle 0.5% max.
F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(MAX)}$=150° C. The SOA curve provides a single pulse rating.
G. The maximum current rating is package limited.
H. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C.
I. For application requiring slow >1ms turn-on/turn-off, please consult AOS FAE for proper product selection.

ALPHA & OMEGA SEMICONDUCTOR

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

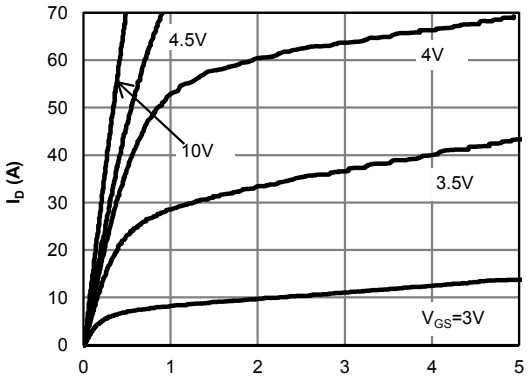


Figure 1: On-Region Characteristics (Note E)

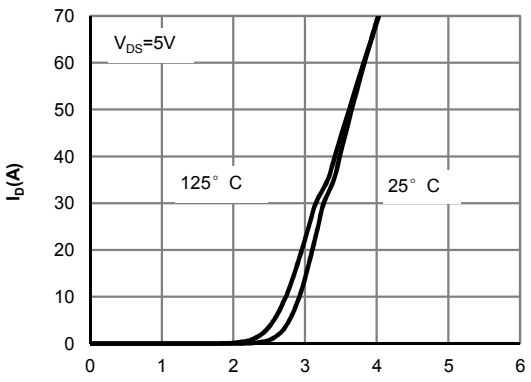


Figure 2: Transfer Characteristics (Note E)

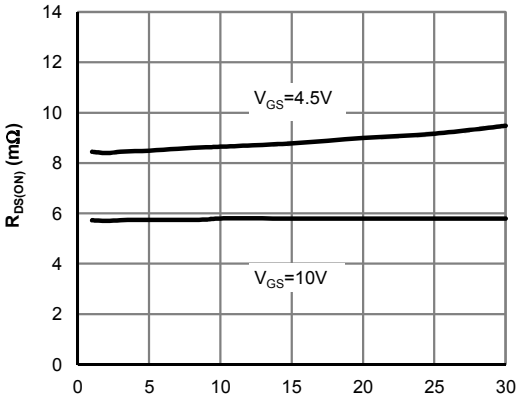


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

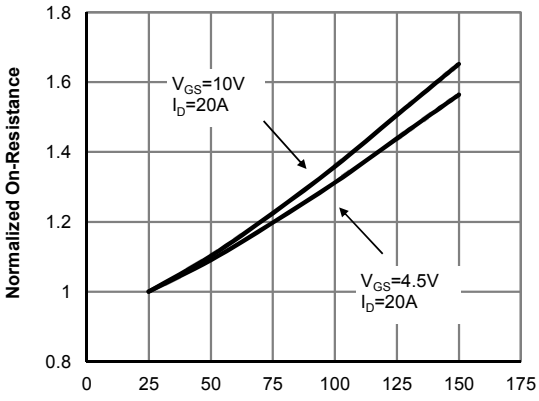


Figure 4: On-Resistance vs. Junction Temperature (Note E)

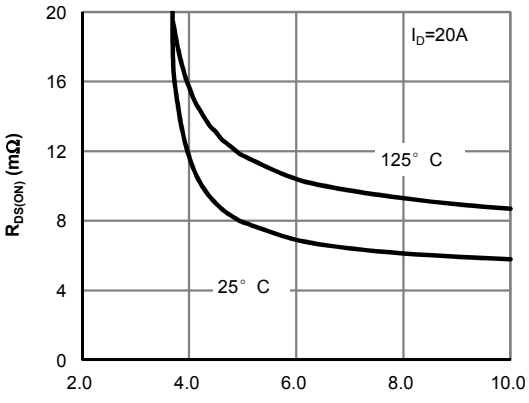


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

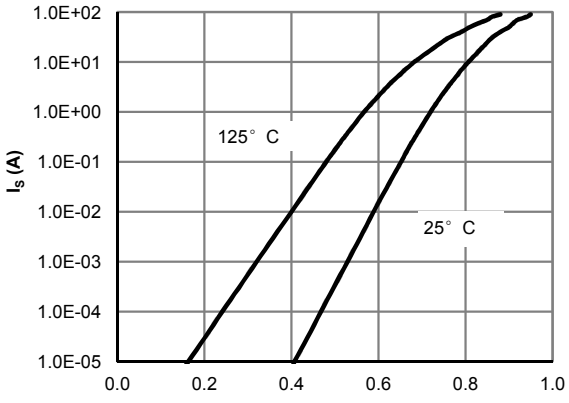


Figure 6: Body-Diode Characteristics (Note E)

ALPHA & OMEGA SEMICONDUCTOR

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

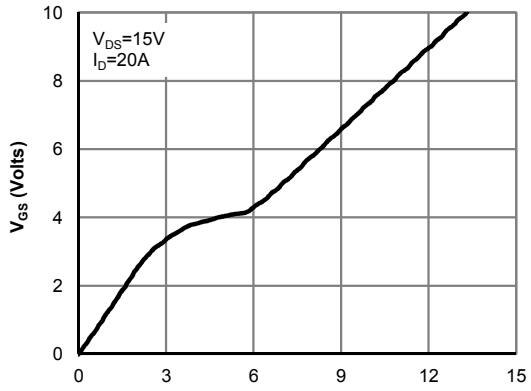


Figure 7: Gate-Charge Characteristics

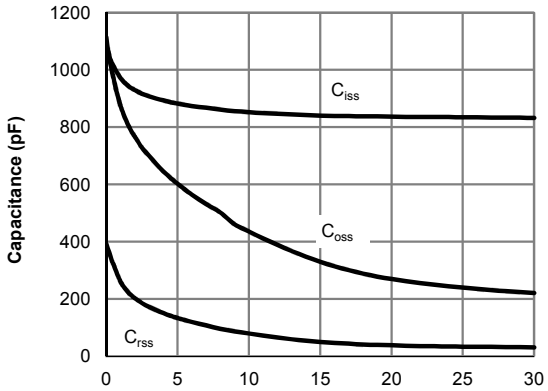
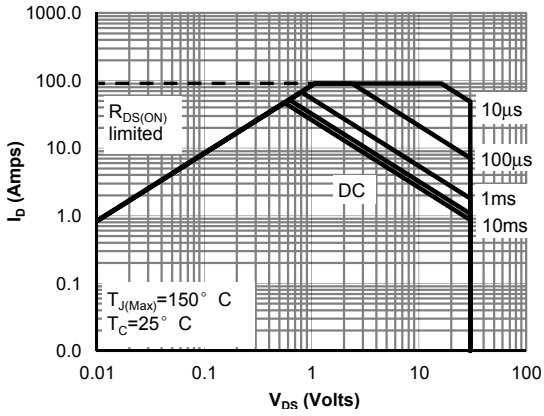


Figure 8: Capacitance Characteristics



V_{GS}> or equal to 4.5V
Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

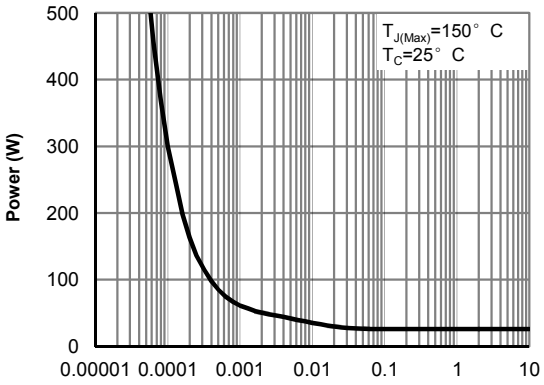


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

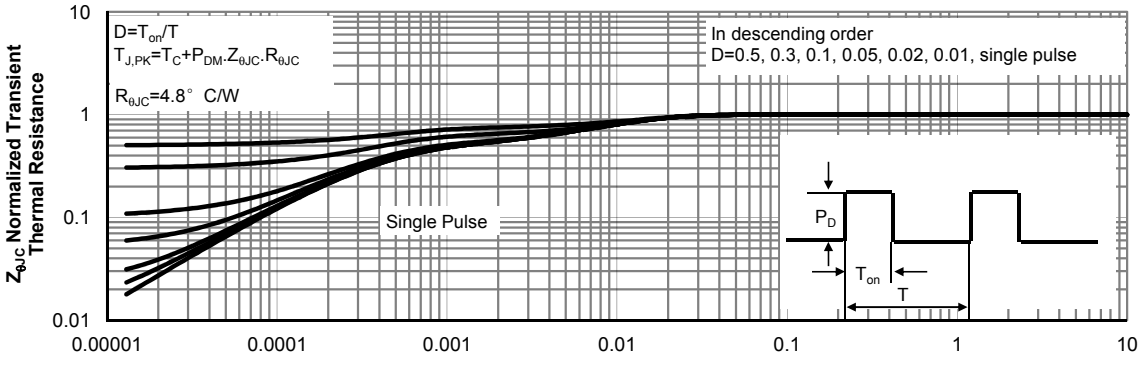


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

ALPHA & OMEGA SEMICONDUCTOR

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

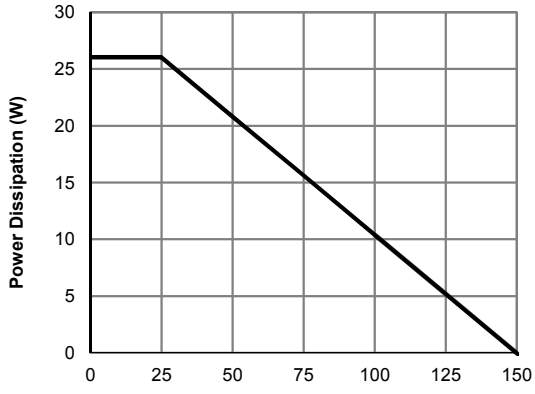


Figure 12: Power De-rating (Note F)

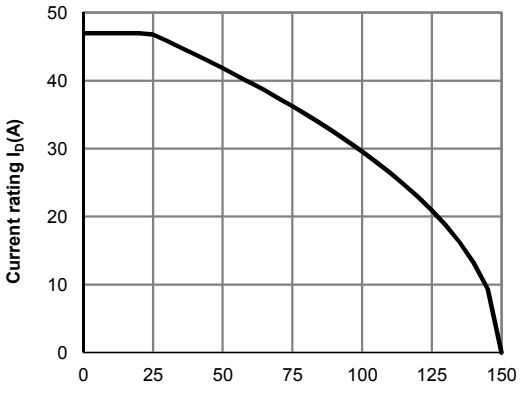


Figure 13: Current De-rating (Note F)

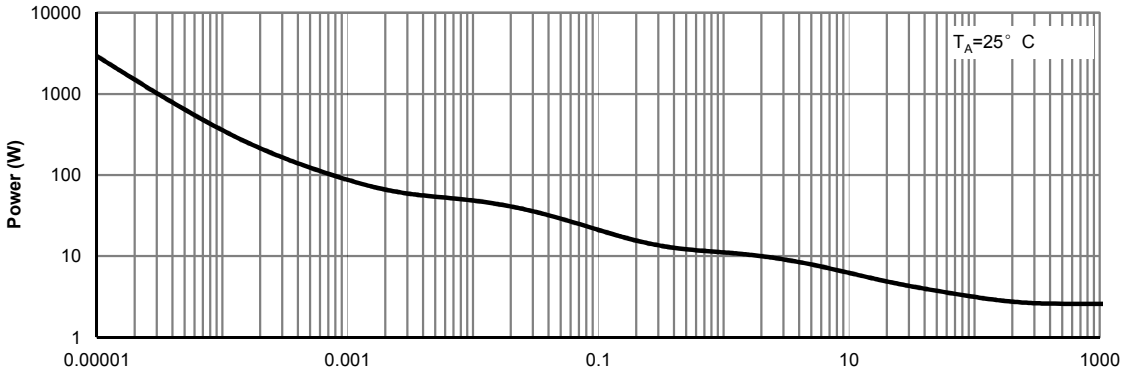


Figure 14: Single Pulse Power Rating Junction-to-Ambient (Note H)

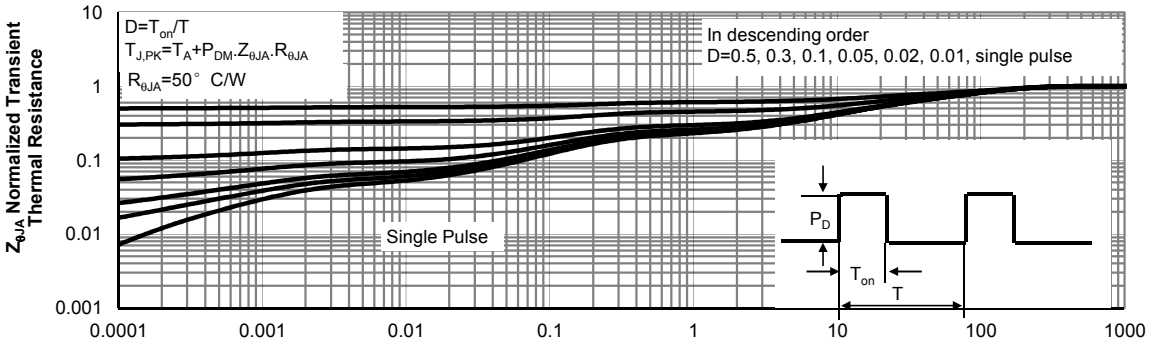
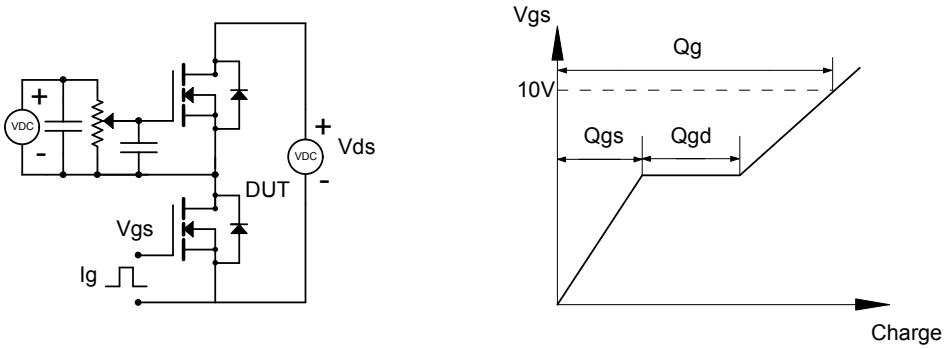
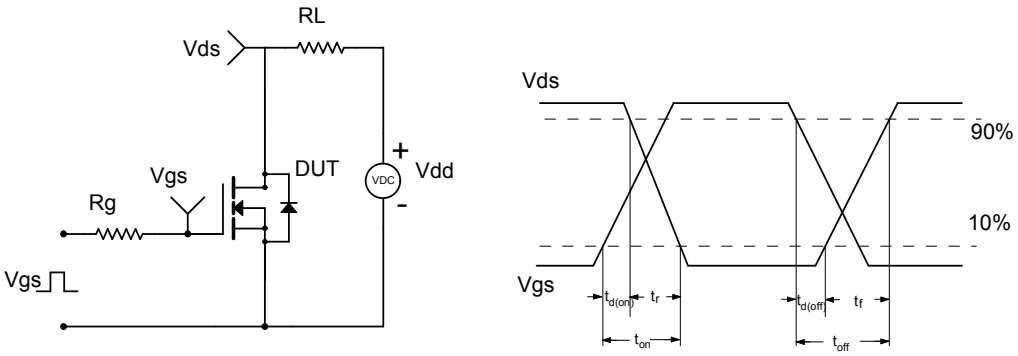


Figure 15: Normalized Maximum Transient Thermal Impedance (Note H)

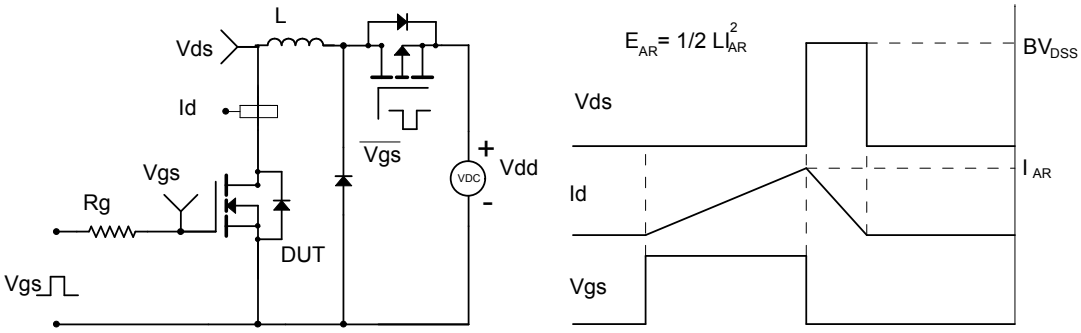
Gate Charge Test Circuit & Waveform



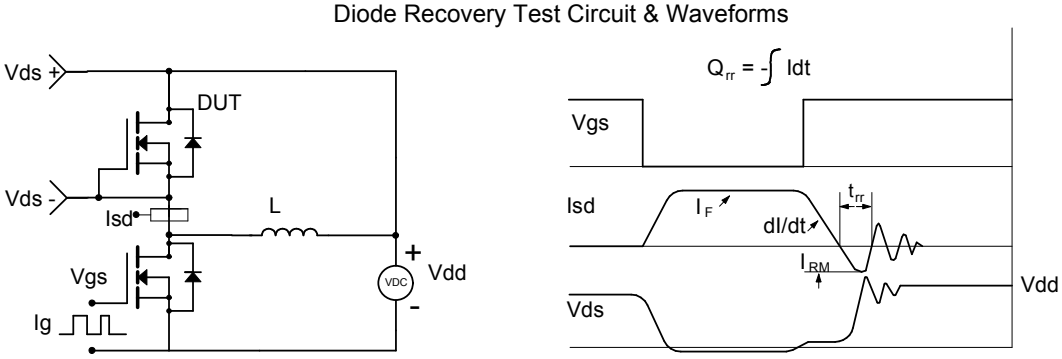
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



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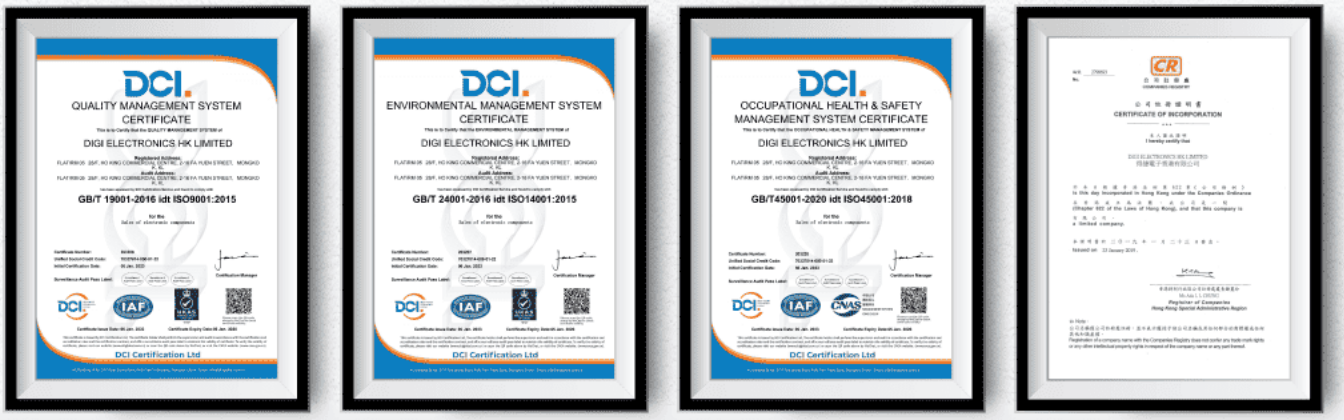

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